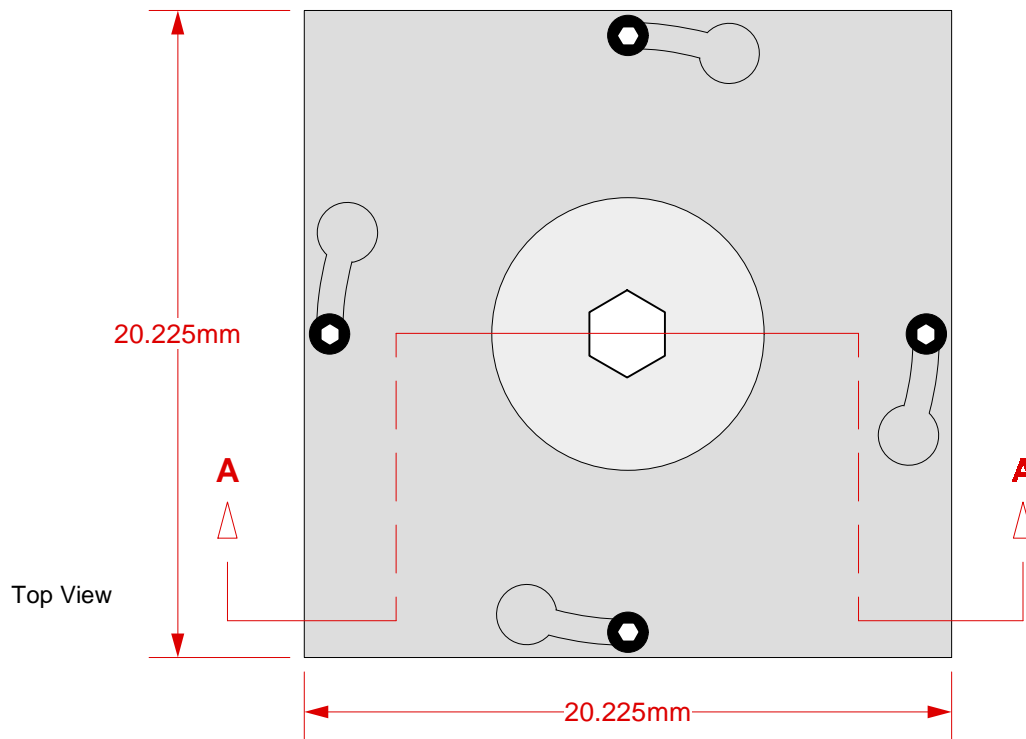


GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

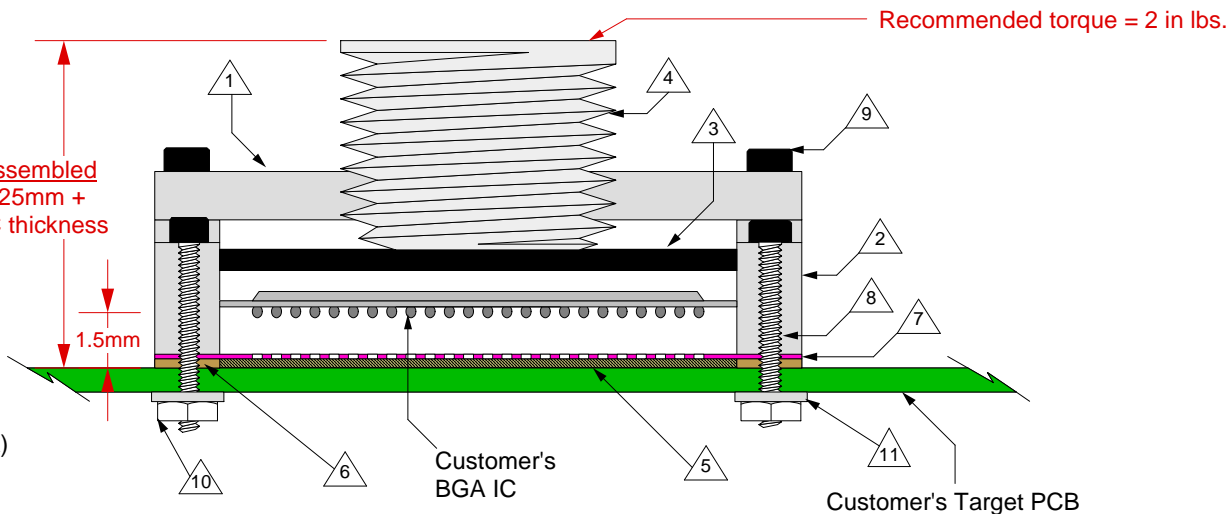


Top View

Assembled
8.25mm +
IC thickness

1.5mm

Side View
(Section AA)



- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

SG-BGA-6229Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

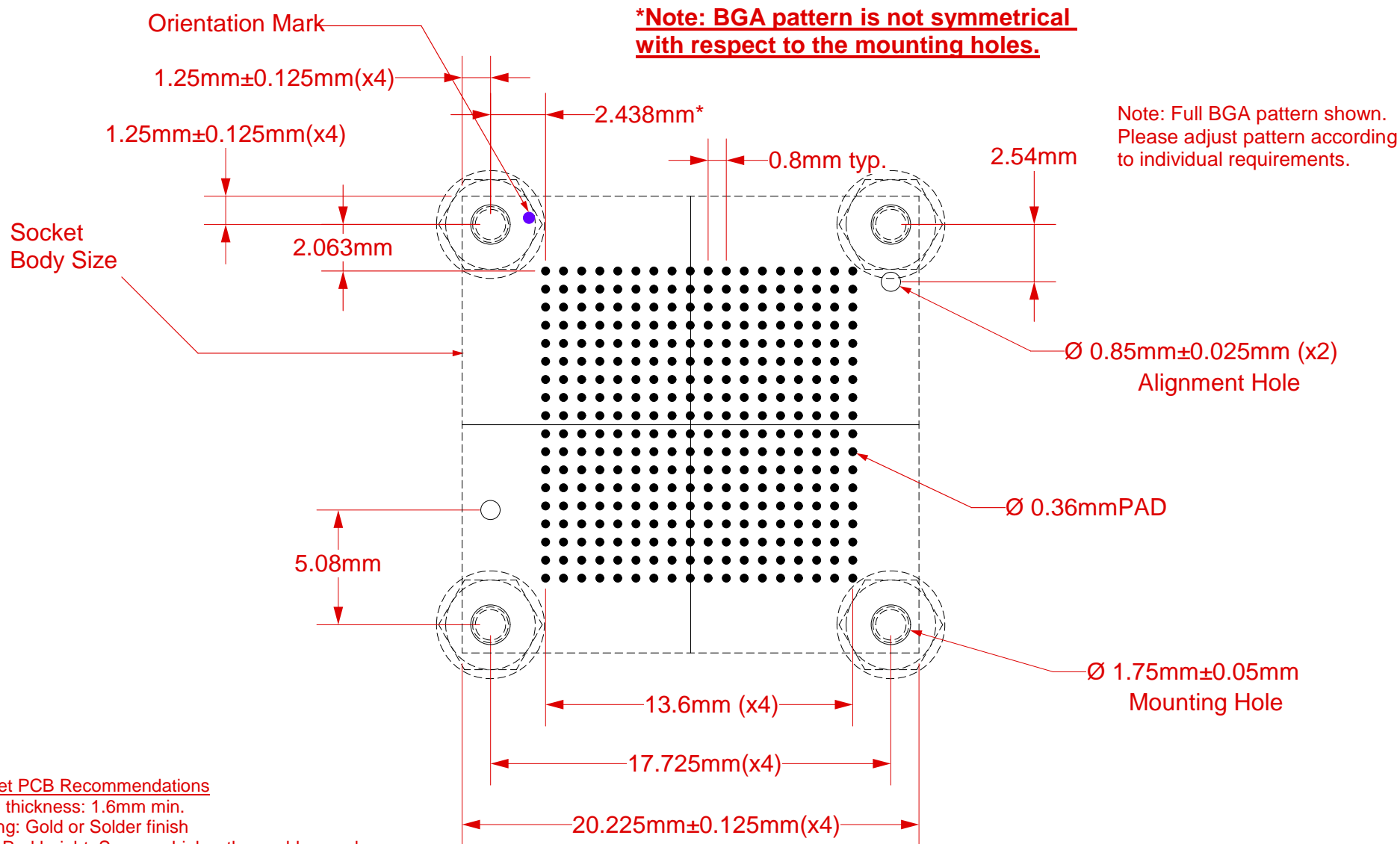
Drawing: J. Glab

Date: 05/24/07

File: SG-BGA-6229 Dwg.mcd

Modified: 7/2/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.




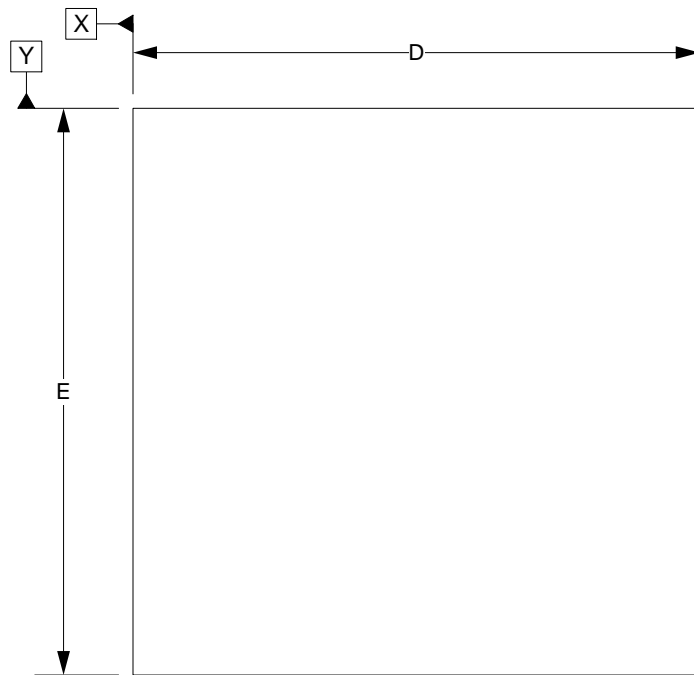
Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

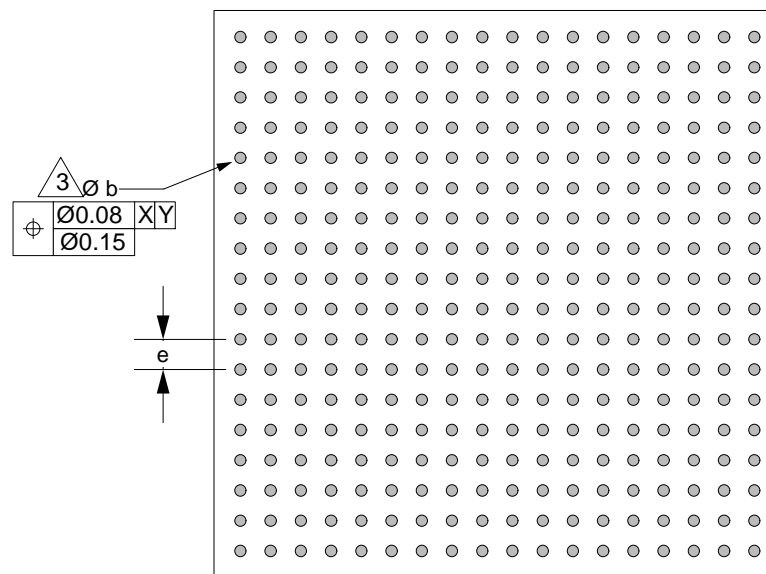
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

	SG-BGA-6229Drawing	Status: Released	Scale: -	Rev: B
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		File: SG-BGA-6229 Dwg.mcd	Modified: 7/2/09, AE	

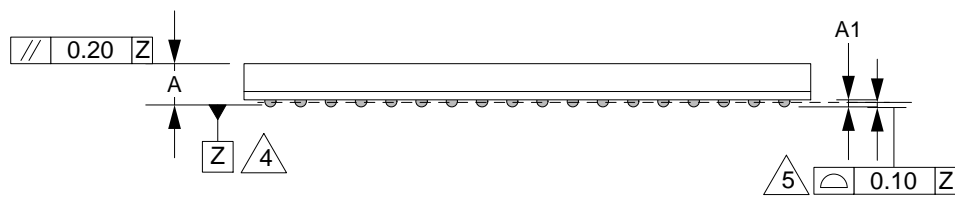


Top View



Bottom View

Array:18x18



Side View

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.



Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.




Datum Z (seating plane) is defined by the spherical crowns of the solder balls.



Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.70
A1	0.21	
b	0.4	
D	15.0 BSC	
E	15.0 BSC	
e	0.8 BSC	

18x18 Array

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	<p>File: SG-BGA-6229 Dwg.mcd</p>	<p>Modified: 7/2/09, AE</p>		